

Specification at page 6, line 3:

A4 Still another aspect of the present invention is the laminated bandpass filter, wherein said first and second strip lines are placed in parallel with each other.

Specification at page 6, line 8:

A3 Yet still another aspect of the present invention is the laminated bandpass filter, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

Specification at page 6, line 14:

A4 Still yet another aspect of the present invention is the laminated bandpass filter, wherein only said first and second strip lines are placed on said dielectric sheet.

Specification at page 6, line 19:

A7 A further aspect of the present invention is a laminated bandpass filter comprising:

Specification at page 7, line 21:

A6 A still further aspect of the present invention is the laminated bandpass filter, wherein said first and second strip lines have the same length, width and position within the plane.

Specification at page 8, line 1:

A9 A yet further aspect of the present invention is the laminated

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A10

bandpass filter, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

Specification at page 8, line 7:

A10

A still yet further aspect of the present invention is the laminated bandpass filter, further comprising:

Specification at page 8, line 23:

A11

An additional aspect of the present invention is the laminated bandpass filter, wherein capacitive coupling of an area where said fourth capacitor electrode and said fifth capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Specification at page 9, line 5:

A12

A still additional aspect of the present invention is the laminated bandpass filter, wherein with respect to said grounding electrode, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of the capacitor electrode connected to said input electrode and the capacitor electrode connected to said output electrode is laminated on a layer superior to said layer.

Specification at page 9, line 17:

A13

A yet additional aspect of the present invention is the laminated bandpass filter, wherein all electrode patterns constituting the capacitor electrode connected to said input electrode and the capacitor electrode

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connected to said output electrode as an input/output capacitance are provided on a layer superior to the layer constituting said strip lines.

Specification at page 10, line 1:

A14

A still yet additional aspect of the present invention is the laminated bandpass filter, wherein with respect to said grounding electrode, an electrode pattern of at least one of said first and second capacitor electrodes is laminated, an electrode pattern of at least one of said first and second strip lines is laminated on a layer superior thereto, and an electrode pattern of at least one of said third to sixth capacitor electrodes is laminated on a layer superior to said layer.

Specification at page 10, line 10:

A15

A supplementary aspect of the present invention is the laminated bandpass filter, wherein said third to sixth capacitor electrodes are provided on a layer superior to the layer constituting said strip lines.

Specification at page 10, line 15:

A16

A still supplementary aspect of the present invention is a laminated bandpass filter comprising:

Specification at page 11, line 21:

A17

A yet supplementary aspect of the present invention is the laminated bandpass filter, wherein said first to fourth strip lines have the same length and width, said first and third strip lines have the same position within the plane and said second and fourth strip lines have the same position within the plane.

Specification at page 12, line 3:

A18
A still yet supplementary aspect of the present invention is the laminated bandpass filter, wherein said first and second strip lines are placed in parallel with each other and said third and fourth strip lines are placed in parallel with each other.

Specification at page 12, line 9:

A19
Another aspect of the present invention is the laminated bandpass filter, wherein said first to fourth strip lines are connected to said internal grounding electrode via a via hole.

Specification at page 12, line 14:

A20
Still another aspect of the present invention is the laminated bandpass filter, further comprising:

Specification at page 13, line 5:

A21
Yet still another aspect of the present invention is the laminated bandpass filter, wherein capacitive coupling of an area where said sixth capacitor electrode and said seventh capacitor electrode overlap each other in the lamination direction forms a jump capacitance.

Specification at page 13, line 12:

A22
Still yet another aspect of the present invention is the laminated bandpass filter, wherein said dielectric sheet is made up of a crystal phase and a glass phase, said crystal phase includes at least one of Al_2O_3 , MgO , SiO_3 and RO_a where R is at least one element selected from La, Ce, Pr, Nd, Sm and Gd

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and a is a numerical value determined stoichiometrically according to the valence of said R.

Specification at page 13, line 21:

A23

A further aspect of the present invention is a laminated bandpass filter, said laminated body incorporating the bandpass filter and the bandpass filter.

Specification at page 14, line 3:

A24

A still further aspect of the present invention is a composite high frequency device, wherein said laminated body incorporates the bandpass filter and another high frequency circuit.

Specification at page 14, line 8:

A25

A yet further aspect of the present invention is a composite high frequency device, wherein electronic parts are mounted on said laminated body incorporating the bandpass filter.

Specification at page 14, line 13:

A26

A still yet further aspect of the present invention is a high frequency device, characterized by comprising the laminated bandpass filter.

Specification at page 14, line 17:

A27

An additional aspect of the present invention is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 15, line 16:

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A still additional aspect of the present invention is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 16, line 20:

A29

A yet additional aspect of the present invention is a laminated bandpass filter manufacturing method comprising the steps of:

Specification at page 29, line 19:

A30

Furthermore, the dielectric layer 505 has strip lines 520 and 521, and the dielectric layer 506 has strip lines 522 and 523. The dielectric layer 507 has capacitor electrodes 524 and 525 and the dielectric layer 508 has an internal grounding electrode 526 and connected to the grounding electrode 510.

Specification at page 34, line 21:

A31

The capacitor electrode 916 is connected to one end 915a of the strip line 915 and the capacitor electrode 912 via a via hole 920 and the capacitor electrode 917 is connected to one end 914a of the strip line 914 and the capacitor electrode 913 via a via hole 921.

IN THE CLAIMS:

A32

4. (Amended) The laminated bandpass filter according to claims 1 or 2, wherein said first and second strip lines are electrically connected to said internal grounding electrode via a via hole.

5. (Amended) The laminated bandpass filter according to